IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Ference et al.

Confirmation No.:

Serial No.:

Group Art Unit:

Filed:

Herewith

Examiner:

Title:

MULTI-CHIP STACK AND METHOD OF FABRICATION UTILIZING

SELF ALIGNING ELECTRICAL CONTRACT ARRAY

To:

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

STATEMENT OF RELEVANCE FOR INFORMATION DISCLOSED BY APPLICANT

Sir:

The following Statement of Relevance is submitted with the accompanying Information Disclosure Citation form.

Document

Designation

Relevance

05-190553

Mounting structure of semiconductor component and manufacture of its

solder bump

JP4088645

Conductive paste and mounting of semiconductor device

Full text copies of the art cited, or the pertinent portions thereof, are enclosed. It is respectfully requested that this art be considered by the Examiner in the above-entitled application and made of record therein. The information provided and references enclosed herewith shall not be construed as a representation that a search has been made or that no other art than that identified exists.

Respectfully submitted,

December 04, 2003

Date

Kevin P. Radigan

Attorney for Applicants

Registration No.: 35,670

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application: Ference et al.

Group Art Unit:

: IBM Corporation

Examiner:

: Intellectual Property Law

Serial No.:

: Mail 972E

Filed: Herewith

: 1000 River Street

Title: MULTI-CHIP STACK AND METHOD OF FABRICATION UTILIZING SELF-ALIGNING ELECTRICAL CONTACT

ARRAY

: Essex Junction, VT 05432

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

INFORMATION DISCLOSURE STATEMENT

It is respectfully requested that the publications identified below and listed on the enclosed PTO 1449 Form(s) be considered by the United States Patent and Trademark Office (USPTO) in the subject United States patent application and be made of record therein. A copy of each publication is enclosed, and this submission is otherwise believed to be in compliance with 37 C.F.R. Sections 1.97 and 1.98. This information is all the material information, as defined in 37 C.F.R. Section 1.56(a), of which the submitter is aware. However, no representation is made or intended that a search has been made or that no other such material information exists.

PATENTS

1. 3,869,787	2. 4,032,058	3. 4,182,781	4. 4,487,654
5. 5,226,232	6. 5,381,307	7. 5,497,258	8. 5,567,295
9. 5,567,654	10. 5,646,828	11. 5,796,591	12. 5,863,406
13. 6,133,637	14. 6,137,184	15. 6,166,556	16. 6,268,739
17. 6,337,522	18. 05-190553	19. JP4088645	, ,

None of the above cited publications, taken singularly or in combination, is believed to teach or suggest the invention as defined by the claims provided in the instant application.

Respectfully submitted,

Dated: December 4, 2003

Telephone No.: (518) 452-5600

Fax No.: (518) 452-5579

By:

Kevin P. Radigan Reg. No. 31,789

INFORMATION DISCLOSURE CITATION (USE SEVERAL SHEETS IF NECESSARY)

ATTY DOCKET NO.	SERIAL NO.
BUR919990304US2	
APPLICANT(S)	
FERENCE ET AL.	
FILING DATE	GROUP

			U.S. PATEN	T DOCUMENT	~S			- 		
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE		NAME		CLASS	SUBC	LASS	FILING DATE IF APPROPRIATE
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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCL	ASS			ANSLATION
	AR	05-190553	07/30/93	Japan	H01L	21/3:	21	No X	YES	ABSTRACT
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FILING DATE

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EXAMINER: Initial here if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not			

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INFORMATION DISCLOSURE CITATION

(USE SEVERAL SHEETS IF NECESSARY)

ATTY DOCKET NO. BUR919990304US2	SERIAL NO.
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FILING DATE	GROUP

HEREWITH

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)				
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EXAMINER	DATE CONSIDERED		
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